

JP7017175 1995-01-20

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Classification:

- international:

B42D15/10; G06K19/077

- european:

Application number:

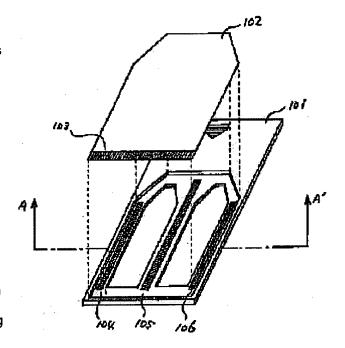
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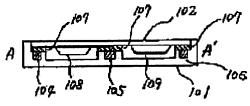
Priority number(s):

Abstract of JP7017175

PURPOSE:To increase a mechanical strength of a memory card even if a dimension of a mounting circuit board is increased and results in a card frame having a larger thin-wall part by a method wherein high-rigidity support materials are integrally bonded to the thin-wall part (to which the mounting circuit board is bonded) of the card frame.

CONSTITUTION:In a memory card having a structure that a mounting circuit board 102 is so embedded and securely bonded in a card frame 101 as to be exposed on the surface of the card, support materials 104-106 are embedded and securely bonded in the card frame 101 so as to be fulsh with a bonding surface of the card frame 101 with the mounting circuit board 102. As a result, the memory card is improved in mechanical strength to twisting, bending, and the like even if the mounting circuit board is increased in dimension and results in the card frame having a larger thin-wall part.





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